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STATEMENT BY APPLICANT	First Named Inventor	Curtis Grant Jones	9
STATEMENT BY AFTERDARY	Group Art Unit	1742	40
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Sheet 1 of 1	Attorney Docket Number	9180-12	

			U.	S. PATENT DOCUMENTS		
Examiner Initials*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document	Pages, Columns, Lines, Where Relevant Passages
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		OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS		
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published		
M	3.	Solomon "Providing High Density and Performance for Chip-to System Interconnection" Advanced Packaging (November 2001) pp 19-28		
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Examiner S	l Signatur	e William Leader (12) 12003	L_	

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.